● WLP-6-03 Power Dissipation (JESD51-7)

Power dissipation data for the WLP-6-03 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition : Mount on a board

Ambient : Natural convection

Soldering : Lead (Pb) free

Board : The board using 4 copper layer.

(76.2mm×114.3mm Area: about 8700mm^2)

1st layer : No copper foil (Signal layer)

2nd layer : 70mm×70mm_Connected to heat-sink.

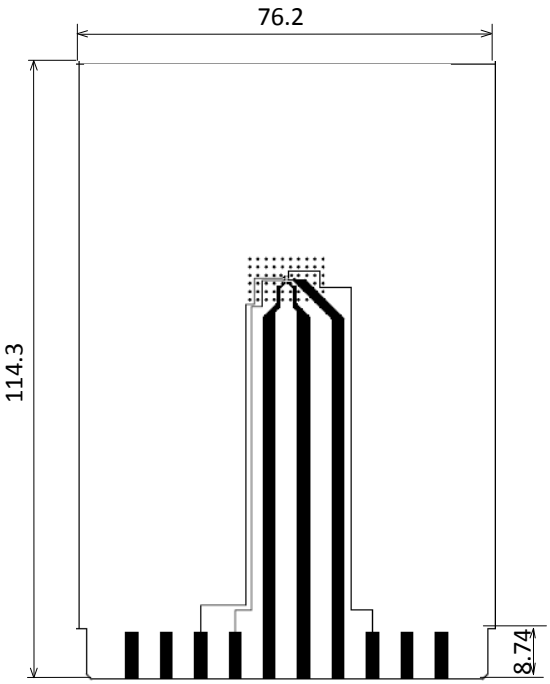
3th layer : 70mm×70mm_Connected to heat-sink.

4th layer : No copper foil (Signal layer)

Material : Glass Epoxy (FR-4)

Thickness : 1.6mm

Through-hole : ϕ0.2mm x 60pcs



Evaluation Board (Unit: mm)

2.Power Dissipation vs. Ambient temperature

Board Mount(Tjmax = 125℃)

AmbientTemperature(℃)	PowerDissipation Pd (mW)	θja(℃/W)
25	840	119.03
85	336